The Valley Megaphone

Newsletter of the Institute of Electrical and Electronics Engineers, Inc., Phoenix Section

July 2014,
Volume XXVIII, Number 7

Executive Committee 2014

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IEEE Phoenix Section on-line updates can be found at http://sites.ieee.org/phoenix/ and on LinkedIn at:http://www.linkedin.com/groups?gid=2765918 and on Facebook at: https://www.facebook.com/IEEEPhoenixSection

Please send announcements for the *Valley Megaphone* to Mahesh Shah at mkshah@ieee.org for inclusion in the Section Calendar.

All meetings announced in the Phoenix Section Megaphone or on the Phoenix Section Calendar are open to everyone (IEEE members and non-Members)

IEEE Phoenix Section 2014 Annual Banquet pictures are available to view and download at http://sites.ieee.org/phoenix/2014/03/03/pictures-from-the-2014-annual-banquet/

Chapters

Signal Processing & Communications
Pavan Turaga
pturaga@asu.edu

Computer Society
Jerry Crow
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CPMT Society
Mahesh Shah
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EMBS Chapter
TBD

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Power & Energy Society
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Women In Engineering
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Young Professionals
Shafiul "Jacky" Islam 520-245-9010
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The Valley Megaphone is the newsletter of the Phoenix Section of the Institute of Electrical and Electronics Engineers. It is published monthly and reaches about 4000 members. Submit articles, advertisements, and announcements to Surinder Tuli at the above email address. Deadline for announcements and advertisements is the third Friday of the month prior to publication. Advertising Rates: Full page: $200, 3/4page: $125, ½ page: $75, 1/3 page: $50, 1/4 page: $25. Change of address/email? Call toll free 1-800-678-IEEE. Please allow 6-8 weeks. Section Web Page is http://sites.ieee.org/phoenix/

U – News

(for Student Members)

Updates of Student Advisors and Committee Members

Each Student Branch noted on the right side of this page should review current information on Advisors and Student Committee Members and forward to my attention within this week, as we are reviewing contacts for reporting and activities including Student Monthly Meetings.

S. Diane Smith
602-749-4601
sdianesmith@computer.org
Student Activities Chair

Start your own MicroMouse and compete for cash prizes!

The Section has a full tournament sized MicroMouse maze. Funding for your project may be available. For details contact the Section Student Activities Chair, S. Diane Smith sdianesmith@computer.org

Student Branches

ASU Main, Engineering
Chair: Jennifer Taggart
928-581-5198,
jennifer.taggart@asu.edu
Advisor: Cihan Tepedelenlioglu,
480-965-6623, **cihan@asu.edu**

ASU Main, Computer Society
Chair: TBD
Advisor: Guoliang Xue
480-965-6218, **xue@asu.edu**

ASU Polytechnic
Chair: TBD
Advisor: TBD

DeVry, Phoenix
Chair: Lori Renaldi
lorirenaldi@computer.org
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dsmith2@devry.edu

DeVry, Computer Society
Chair: TBD
Advisor: Diane Smith
dsmith2@devry.edu

NAU, Engineering
Chair: TBD
Advisor: Niranjan Venkatraman
v.niranjan@ieee.org

Embry-Riddle, Prescott
Chair: Lisa M. Ferguson
FERGUSL2@my.erau.edu
Advisor: John E. Post
postj@erau.edu

U – Newsbytes

ASU Polytechnic is currently seeking Advisor for the Student Branch. Please email Diane (at email address above) with Recommendations.

This month we had a meeting and a presentation about the High altitude balloon experiments done by ASU and ERAU was shown at the monthly meeting. DR Cone and ten other persons attended the banquet in Phoenix. There was a lunch and learn held at the Hazy library (ERAU campus library) about the type of articles and media available for research from the IEEE in our library and how to access it. The group also sponsored a representative from labview to come and demonstrate their product for a large group of people.

Our group did sponsor an "egg drop" contest for campus engineering week. The Idea was to get students involved to design a device in which an egg can survive a drop from a 3 story building. The criteria for the contest was based on the weight, number of pieces of the device, and if the device hit the target. I do have pictures from the event if you would like to see them.

Thank you
Brenda Moerchen
Secretary, ERAU Chapter, Prescot

Upcoming Conferences in June in Region 6

There are 11 conferences in Region 6 during the month of July. There are two in Oregon, 5 in California, 1 in Nevada, 1 in Hawaii, 2 in Alaska, and none in Arizona.

We are starting to work on plans for a Metro Area Workshop for Phoenix in March of next year (2015). If anyone would like to volunteer, please contact your society local chapter or myself at Phoenix.conferences@ieee.org. If there are suggestions for topics or speakers, please contact the above mentioned officers.

Our goal is to provide solid education (with CEUs) and an opportunity to network and meet fellow engineers, all at an affordable price.

Look forward to seeing you there.

If you have any suggestions for speakers, or if your group is looking to have a conference in Arizona, please contact our new direct email Phoenix.Conferences@ieee.org

Call for Papers
28th International Conference on Microelectronic Test Structures

March 23-26, 2015, Phoenix, Arizona USA

General Chair:
Larg Weiland
PDF Solutions
larg.weiland@pdf.com

Technical Chair:
Colin McAndrew
Freescale Semiconductor, Inc.
Colin.McAndrew@freescale.com

Tutorial Chair:
Brad Smith
Freescale Semiconductor, Inc.
Brad.Smith@Freescale.com

Local Arrangements:
Colin McAndrew
Freescale Semiconductor, Inc
Colin.McAndrew@freescale.com

Equipment Exhibition:
Bill Verzi
Agilent/Keysight Technologies
bill_verzi@agilent.com

Asian Representative:
Kunihiro Asada
VLSI Design and Education Center
University of Tokyo
asada@silicon.u-tokyo.ac.jp

European Representative:
Anthony Walton
Scottish Microelectronic Centre
University of Edinburgh
Anthony.Walton@ee.ed.ac.uk

USA Representative:
Loren Linholm
linhlw@comcast.net

Conference Manager:
Wendy Walker
Widerkehr and Associates
wwalker@widerkehr.com

The 28th International Conference on Microelectronic Test Structures (ICMTS) will be held in Phoenix, Arizona, USA, bringing together designers and users of test structures to discuss recent developments and future directions. The conference will be held March 24-26, 2015, preceded by a one-day Tutorial Short Course on Microelectronic Test Structures on March 23. There will be an equipment exhibition relating to test structures and measurements. Original papers are solicited presenting new developments in test structures, as well as their implementation, measurement, and application, related to semiconductors, nanotechnology, and MEMS. A Best Paper award will be presented by the Technical Program Committee. The conference is sponsored by the IEEE Electron Devices Society and all published papers will be posted to IEEE Xplore®.

Topics of relevance to ICMTS include, but are not limited to:

Material and Process Characterization: Wafer material evaluation for SiGe, strained Si, Si-on-insulator, Ge, GaAs, GaN and other compounds. Resistivity, mobility, stress, contact resistance, dielectric, and interconnect measurements. Test structures and methods to evaluate new materials and devices, e.g. graphene and CNTs.
Test structure design methods: Flows for automated test structure design, generation, and verification; design-for-analysis, parameterized design, layout issues (grid, hierarchy, misalignment), switched arrays.
Replicated Feature Metrology: Level-to-level registration, overlay, CD uniformity and control, non-electrical characterization techniques, mask and reticle process control.
Manufacturing of Integrated Circuits and MEMS: Evaluation of individual and groups of integrated circuit, device, and MEMS process steps and elements: transistors, diodes, mechanical structures, device isolation, memory cells, and interconnect. Assessment of MMICs and RF components and products. Evaluation and optimization of standard cell macros and other circuits.
Reliability and Product Failure Analysis: Test structures for quality assurance, transistor, thin film, dielectric, and interconnect reliability, thermal monitoring and analysis, accelerated wafer level tests, wafer level burn-in, failure identification, reliability prediction.
Nanotechnology, Displays, and Emerging Devices: Test structures and methods to evaluate nanotechnology (materials and devices), displays, optoelectronic materials and devices, novel memories, and related materials.
(BIO-)MEMS, (BIO-)Sensors, and Actuators: Test structures for MEMS and micromachining including physical/chemical/optical/bio sensors, photonic devices, amorphous silicon films and devices.
Device and Circuit Modeling, Parameter Extraction: Model parameter extraction, RF device modeling, de-embedding, pulsed measurements, DC and high frequency measurement techniques and applications.
Technology R&D, Integration, and DFM: Test structures for FEOL or BEOL evaluation, design rule determination, process uniformity and worst-case analysis, test structures to assess integration and new technologies, switched array test chips/devices for large scale evaluations and reduced pad count.
Test Circuits: Novel on-wafer circuits for characterization of manufacturing technologies, variability, yield, and performance. Circuits to simplify probing, improve measurement robustness, and reduce pad count.
Yield Enhancement, and Production Process Control: Yield enhancement structures and methods, critical area calculation, defect estimation structures and methods, yield modeling, evaluation of design-manufacturing interactions, place and route methodology, and statistical process control. Large-scale, many-component test arrays and multiplexing techniques for technology assessment.
Test Structure Measurement Utilization Strategy: Test equipment, probing and programmable testing for process diagnostics, optimizing test throughput, database and data analysis methods, statistical data analysis, expert systems and related techniques, including capacitance, voltage, current, resistance, optical, and thermal measurements.
Matching and Variability Test Structures: Matching and variability of components (transistors, resistors, capacitors, inductors) and layout for circuit applications and their evaluation. Characterization of identically designed components. Modeling of matching and variability.

Authors are asked to submit an abstract of up to four pages in PDF format (font-embedded). The first page **must** consist of a title, a 50-words summary, author name(s), the full address, fax number, and e-mail address of the lead author, and author preference for oral or poster session presentation, if any. The body of the abstract should be three pages or less consisting of one page of text (800 to 1000 words) and up to two pages containing major figures and tables. Please visit the ICMTS 2015 official web site icmts2015.pdf.com for further information and paper submission. You may care to join the ICMTS group at www.linkedin.com.

The selection process will be based on the technical merit and will be highly weighted in favor of papers that have a high test structure content, include measured data and analysis, together with illustrations of the test structures involved. The submission deadline is **October 17, 2014**. Notice of paper acceptance, with instructions for manuscript preparation for the conference proceedings, will be sent to the authors of the papers selected for presentation by early December, 2014. The deadline for submission of the final paper will be January 20, 2015.

Details of the venue, hotel, registration, etc. will be posted at icmts2015.pdf.com as they are finalized.

For further technical information, please contact the technical chair:
Colin McAndrew, Freescale Semiconductor, Inc., Colin.McAndrew@freescale.com

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

2014 Executive Committee for CPMT Chapter for IEEE-Phoenix Section

Position	Name	Phone Contact	Email Contact
Chair	Dr. Mahesh K. Shah	(480) 544-9438	mkshah@ieee.org
Asst. Chair	Mr. Vivek Gupta	(480) 734-2366	vmgupta@msn.com
Secretary	Dr. Devarajan Balaraman	(480) 619-0944	iamgoinbiking@gmail.com
Treasurer	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Program Chair	Mr. David Dougherty	(480) 245-8099	david.dougherty@freescale.com
Asst. Program Chair	Dr. Nageswara R. Janapala	(650) 213-6733	nageswara.r.janapala@intel.com
Tutorial Chair	Dr. Ashish Gupta	(480) 554-2409	ashish.x.gupta@intel.com
Asst. Tutorial Chair	Adel Elsherbini	(734) 686-2278	a.elsherbini@gmail.com
Workshop Chair & Publicity	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Website Co-Chair	Huiyang Fei		Huiyang.H.Fei@ieee.org
Website Co-Chair	Bharat Penmecha	(480) 552 2511	bharat.penmecha@ieee.org

Tentative Schedule for Monthly Seminars

We are working to arrange monthly Seminars on topics of interest to our members. If you have suggestion for topics and/or speakers please contact any of the executive committee members listed above.

July 16 – Dr. Dev Gupta - Improved PoP Package w/o TSVs can compete with 2.5/3D Packages using TSVs
August – Dr. Darrel Frear – Packaging Needs for Automotive Radar
September – Dr. Jon Harris – Packaging for LED Lighting
October – Dr. Stuart Bowden – Solar Cells
November – Dr. Jaynal Molla – Plating for Electronic Packaging

Additional Activities –Tutorial and Workshop

Phoenix section is planning to hold a Half Day tutorial on the topic of **Reliability Engineering** in early Fall. In addition we are working with other Society Chapters to hold a workshop on **Emerging Device and Packaging Technology** in late November or Early December. Please wait for announcements in near future

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Wednesday, July 16th, 2014 at 5:30 PM

Improved PoP Package w/o TSVs can compete with 2.5/3D Packages using TSVs

Dr. Dev Gupta
Chief Technical Officer
***APSTL* (*A*dvanced *P*ackaging & *S*ystems *T*echnology *L*aboratories) LLC**
Scottsdale, AZ 85262 USA
dgupta@apstl.com

ABSTRACT

The industry has been awaiting maturation of 3D packaging technologies as a high - performance & versatile alternative to further integration on a single die. So far die stacking & interconnecting with Through Silicon Vias (TSVs) have received most attention. The commercial adoption of 3D TSVs has been limited to cases where its use has resulted in performance benefits and reduced costs, e,g. BSI modules used in some Smart Phones. Cost reduction has been a key factor behind the adoption of 2.5D for small-scale production of high-end FPGAs for which a single large chip is replaced by several smaller chips in a multi-chip module rather than a single large chip and thus reduce yield losses in the Wafer Fab. Such cost reduction has not yet been possible for CPU-Memory combinations in 3D stacks. This is not simply because of the high initial cost or supply-chain issues typical of new technologies, but also due to unresolved technical issues related to choice of material and process flow for 3D TSVs. These concerns, along with stress and thermal issues that affect device performance in 3D stacks, will be discussed. Lower-risk alternatives that can be implemented even in consumer systems e.g. Smart Phones were evaluated. To identify "low hanging fruits", analyses was carried out to simulate bandwidth and power needed to transfer data in 3D stacks and 2.5D modules using TSVs as well as several packages that do not have to use TSVs for application to Smart Phones. PoP (Package-on-Package), the poor man's 3D is ubiquitous in Smart Phones. This talk will describe efforts underway at APSTL to improve PoP package electrical performance e,g. power efficiency (battery life) and bandwidth (video rate) to approach that of 3-d stacking with TSVs but without using any TSVs on the active dies. Improved performance of the resulting "Super PoP" will be discussed and contrasted with other industry efforts to improve the PoP package.

BIOGRAPHY

Dr. Dev Gupta has been pioneering and innovating various types of Advanced Packaging technologies e,g. Flip Chip (electroplated solder bump, bonding robots, pillar and micro - pillar bumps, organic substrates) at Motorola and Intel that have now become industry standards. At Intel, Dr. Gupta's Team succeeded in dramatically improving the yield & reliability of Organic Substrates, thus enabling the widespread adoption of flip chip technology. At APSTL he is responsible for the development and licensing of new Advanced Packaging technologies e,g. various types of bumping & substrate, their assembly (as well as turnkey engineering of fabs for them), and now the "Super PoP" technology that he will discuss in his talk.

Date: Wednesday, July 16th, 2014

Location: Spectrum Conference Room, Freescale Semiconductor, Inc., 2100 E. Elliot Rd. Tempe, AZ. There are new signs on the property (Discovery Business Center). Enter the facility through the Main (South) Lobby in building 94 and sign in with Security (*Photo ID required*). You will be escorted to the meeting room.

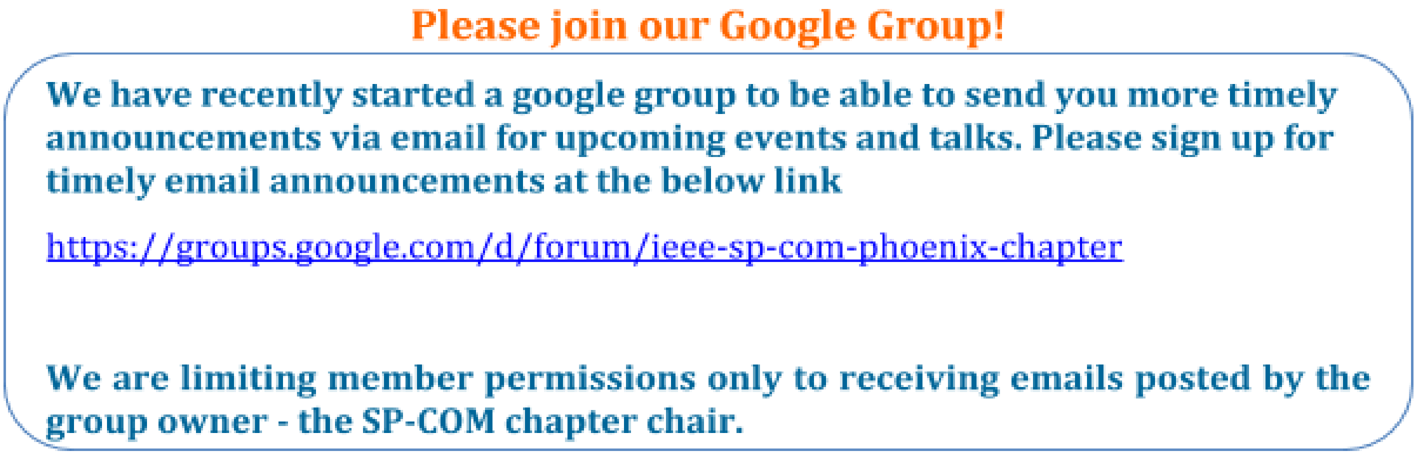
Agenda: 5:30–6:00 PM: Social/Refreshments, 6:00–7:00 PM: Presentation, 7:00 PM: Dinner
(Pizza and Soda will be provided by the IEEE Phoenix Section CPMT Society Chapter)

IEEE members and non-members are all welcome to attend. Those who plan to attend should be at the facility entrance no later than 5:45 PM, as there will be no escorts available after that.

For more information, please contact any of the following CPMT officers:

Vasu Atluri	(480) 227-8411	Devrajan Balaraman	(480) 619-0944	David Dougherty	(480) 413-6923
Adel Elsherbini	(734) 686-2278	Ashish Gupta	(480) 554-2409	Vivek Gupta	(480) 734-0266
Nageswara Rao J.	(650) 213-6733	Mahesh Shah	(480) 544-9438		

SP-COM Phoenix Chapter



Please join our Google Group!

We have recently started a google group to be able to send you more timely announcements via email for upcoming events and talks. Please sign up for timely email announcements at the below link

https://groups.google.com/d/forum/ieee-sp-com-phoenix-chapter

We are limiting member permissions only to receiving emails posted by the group owner - the SP-COM chapter chair.

Technical Co-Sponsorship by the IEEE Signal Processing and Communications Chapter, Phoenix Section

We continue to post meeting notices on IEEE vtools at (https://meetings.vtools.ieee.org/main)

Phoenix Chapter of the IEEE Computer Society

July, 2014

News

- Chapter meeting dates for the two remaining meetings this year are Sep 3rd and Nov 19th. Both dates are Wednesdays, but note that the 19th is third Wednesday. Both meetings will be held at DeVry University. Mark your calendars to save the dates.
- There have been a number of inquiries regarding the possibility of again holding meetings in the east valley as we did for most of last year. We are actively seeking a suitable venue in the east valley. Once secured, we will begin holding every other meeting at the new location.
- On July 2nd Jack Ring of OntoPilot gave a presentation on "The Fundamental Foundation for Successful Systems" in which he detailed a unique new methodology, developed locally by OntoPilot, for software integrity assurance. The presentation was well received – a fact evidenced by the numerous questions and the post-presentation discussions.

Future Events

- On September 3rd we expect to have a speaker from ASU giving a presentation on attack vectors for authentication by picture image.
- On November 19th Hal Berghel, our presenter in March, will return to provide us a presentation on "The Modern Surveillance State".

Meetings start at 6:00 pm with networking and light refreshments followed by the presentation at 7:00 pm. DeVry University is located at 2149 W Dunlap Avenue, Phoenix, (a mile east of I-17 on Dunlap).

Visit the CS Chapter website for the latest information: http://ewh.ieee.org/r6/phoenix/compsociety/.
For brief announcements regarding upcoming events we are also on Twitter: @IEEECS_PHX

If you would like to suggest a topic or speaker for any of our future meetings, please contact one of the chapter officers:

Chair: Jerry Crow (jerry.crow@computer.org)
Vice-chair: Brad Morantz (bradscientist@ieee.org)
Secretary/Webmaster: Audrey Skidmore (askidmore@computer.org)
Treasurer: Diane Smith (sdianesmith@computer.org)

IEEE Power and Energy Society
Phoenix Chapter
http://www.ewh.ieee.org/soc/pes/phoenix/

News and Announcements:

- Want to know more about IEEE Power and Energy Society? Watch this video:
  - http://www.youtube.com/watch?v=BRKM4lpo_tk
  - More videos are available at: http://ieee-pes.org/outreach/pes-informational-promotional-videos

- Have you considered becoming a Senior Member of IEEE? It's not as difficult as you think. Basically, you need ten years of professional experience, and your bachelor's degree counts for three of those years. Find out more at: http://www.ieee.org/membership_services/membership/senior/index.html

57th ANNUAL IEEE-PES FUNDRAISING GOLF TOURNAMENT

IEEE
PES
Power & Energy Society®

NOVEMBER 15, 2014

Be sure to join us at Rio Verde Golf Club, located at 18731 E 4 Peaks Blvd, Rio Verde, AZ 85263, for a 12:45 PM Shotgun Start. The course is located 10 Minutes north of Fountain Hills. (480) 471-9420 http://www.rioverdecc.com/Map

This is the annual fundraiser for your IEEE-PES Chapter. The fee is $100 per player or $400 to sponsor a foursome. Be sure to come early and stay late as there will be free range balls beforehand and dinner afterwards. Cash prizes awarded for first place, second place, and third to last place teams. There will also be a Raffle, Skills Games, and Giveaways Galore.

Use this sheet to sign up either individually or for your team. You can either:

- **Print out and complete, then mail the form with your payment**
- **Return this form electronically (distribution@gorman-co.com) and then send your payment.**
- **Send payments to:** **IEEE-PES**
  c/o Gorman Company
  4819 35th Street
  Phoenix AZ 85040

You will be notified via email that your payment has been received and you are registered to participate. If you have any questions, please feel free to call us at (602) 470-0400.

Please provide all requested information, including email addresses for all team members.

TEAM/SPONSOR____

Player ____________________________________ **Dinner?**____

Email ____

Player ____________________________________ **Dinner?**____

Email ____

Player ____________________________________ **Dinner?**____

Email ____

Player ____________________________________ **Dinner?**____

Email ____

Additional Dinner Guests: ______________________________

To minimize waste and extra costs, we would like your help getting an accurate dinner count.

INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS

WAVES AND DEVICES

PHOENIX CHAPTER

http://ewh.ieee.org/r6/phoenix/wad/

2014 Calendar

Date	Location	Topic / Title	Speaker	Affiliation	IEEE Society
29-Jan	ASU Brickyard	Expanding your knowledge of Laser Fusion and Optical Accelerators	Ken Barat	Consultant	Photonics
6-Mar	ASU Goldwater	Embrace Circuit Nonlinearity to get Transmitter Linearity and Energy Efficiency	Earl McCune	MTT DML	Microwaves
4-Apr	Agilent	Current and Future Trends in Photovoltaics Technologies	Christina Honsburg	ASU	Electron Devices
25-Apr	Freescale	Bio Medical Devices	Jennifer Christen	ASU	Electron Devices
1-May	ASU	Software Defined Radio	Hossein Hashemi	USC	Microwaves/ Electron Devices
22-May	ASU	Antennas	Kathleen L. Melde	UofA	Antennas
Sept	**TBD**	**Device Modeling**	**Colin McAndrew**	**Freescale**	**Microwaves / Electron Devices**
Oct	**TBD**	**Antenna System**	**Ron Lavin**	**Boeing Corp.**	**Antennas**
Nov	**TBD**	**Microwave Board Materials**	**John Coonrod**	**Rogers Corp**	**Microwaves**

Phoenix Section Life Member Affinity Group

Technical & Administrative

Meeting October 14, 2014

Program Presentation: TBD

Meeting Agenda: TBD

Where: SRP's **PERA Club** Bighorn Room,
1 East Continental Drive, Tempe, AZ
Continental is West of 68th St., ½ mile south of McDowell Road
Enter the Private PERA Club and follow drive to large parking lot. Big Horn Room is the most South east building off parking.

When: Tuesday, October 14, 2014, 11:00am – 1:00pm, Registration fee is $15. This fee will include lunch provided by the PERA Club. Lunch will be: to be voted on

RSVP:
The Program Chair is seeking suggestion from members for future presentations. Any ideas of interest to LM are open for consideration. Please contact Ronald Sprague Program Chair at r.sprague@ieee.org or any officer with ideas.

About IEEE Phoenix Section Life Member Affinity Group:

The IEEE Phoenix Section Life Member Affinity Group was organized to enable IEEE Life Members to retain active IEEE associations, contribute to the social good in their communities, advance IEEE's professional interests and enjoy each other's company.

Activities: Technical meetings scheduled in February, May, October, and December. Elections are held at the December meeting.

Future Technical Meetings: All meeting are scheduled at the SRP PERA CLUB. It is suggested you put these dates on your calendar to attend our meetings.

- Tuesday, October 14, 2014
- Tuesday, December 9, 2014

Officers:

Chair	Leslie Daviet II	lesdavietii@cs.com
Vice Chair	Position is Vacant	
Secretary	Tom Lundquist	Tom.Lundquist@ieee.org
Treasurer	Leslie Daviet II	lesdavietii@cs.com
Program	Ronald L. Sprague,	r.sprague@ieee.org
Past Chair	A. Barry Cummings	abarrycummings@gmail.com

IEEE Young Professionals (formerly GOLD) Phoenix Section Executive Board

- Chairman: Shafiul “Jacky” Islam (shafiul.islam@intel.com)
- Vice Chair: Jennifer Taggart (jennifer.taggart@asu.edu)
- Secretary/Webmaster: Joseph Caglio (joseph.m.caglio@intel.com)
- Treasurer: Ashley Meredith (ashley.meredith@aps.com)

May 28, 2014, IEEE Young Professionals Phoenix Art Museum Trip

As our social event for May, we explored Phoenix Art Museum as a group.

Organizer: Ashley Meredith (ashley.meredith@aps.com)

June 20, 2014, IEEE Phoenix Young Professionals Movie Night

We had a movie night on June 20th at 7:40pm at Harkins Theater Arizona Mills, 5000 Arizona Mills Cir. Tempe, AZ 85282.

There were about 12 attendees who had the chance to mingle with fellow young professionals. Unfortunately, “Edge of Tomorrow” was not showing at that time and as a group, we voted to watch “Godzilla” as an alternative.

Organizer: Ashley Meredith (ashley.meredith@aps.com)

June 29, 2014, Officers’ Meeting

All of the four officers attended an officers’ meeting on June 29 from 7:00pm to 9:00pm over Google Hangouts to discuss our event plan and budget for Fall. We are expecting to have a Career Mixer, Speaker Series, Social events, and a Virtual Leadership Conference. We also discussed about sending out surveys, website, collaboration tools, social media, and Polo / T-Shirts. We will be providing more details as we finalize and implement our plans.

Organizer: Shafiul “Jacky” Islam (shafiul.islam@intel.com)

July 4, 2014, Independence Day (United States) Celebration

Come celebrate the 4th of July at the Tempe Beach Park party with IEEE Young Professionals Phoenix Section. Enjoy music and food from various vendors. Tickets can be bought early for $5 at all Fry's Food Stores until July 3rd. Tickets can also be bought at the gate for $8. We will meet at the main entrance at 7pm. More information can be found at http://www.tempe4th.com/index.asp with locations for parking spots and road closures. Friends and family are welcome to attend! Hope to see you there!

Please take a moment to register (so that we have a roster of attendees) at:
https://meetings.vtools.ieee.org/meeting_view/list_meeting/27045

Please contact Joseph Caglio (joseph.m.caglio@intel.com) with questions.

2014 IEEE Phoenix Section News

Executive Committee Meeting

No meeting of Executive Committee in July & August
Normal meetings are on first Tuesday of the month from 6:00 PM to 8:00 PM
The Airport Hilton Phoenix,
2435 S 47th St. Phoenix, AZ 85034, (480) 894-1600.

2014 Executive Committee

Chair:	Barbara McMinn
Vice Chair:	Bruce Ladewig
Secretary:	Surinder Tuli
Treasurer:	Vivek Gupta
Past Chair:	Charles Weitzel

Executive Committee Meetings

Date: First Tuesday of every month, except July and August
Time: 6:00 – 8:00 p.m.
Location: Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, AZ 85034

IEEE Phoenix Section Annual Banquet 2014 Photos are Posted at:

http://sites.ieee.org/phoenix/2014/03/03/pictures-from-the-2014-annual-banquet/

IEEE Phoenix Section – Forming Reliability Chapter

Reliability Chapter Forming

The IEEE Reliability Society (IEEE RS) plans to collaborate with the IEEE Phoenix Section, as well as, the IEEE Sections in Tucson and Sierra Vista/Ft Huachuca in forming this new state-wide IEEE Reliability Chapter. The Reliability Chapter will focus on 3 meetings in the first 6 months after being created. The topics that may be discussed will include new IEEE Reliability Standards (e.g., IEEE 1633), new software reliability techniques and reliability growth techniques. The IEEE RS plans to rotate Chapter meetings between the 3 state locations. If you are a member of the IEEE, but not an IEEE-RS member, you could join the society for $35 and be a charter member to help in the formation of this new Chapter. If you are an IEEE RS member or interested in Reliability Society, please contact Lou Gullo at **Louis.Gullo@ieee.org**.

IEEE Senior Member and Fellow Grade

IEEE Phoenix Section Membership Development would like to nominate eligible IEEE Members from the Section to Senior Member and Fellow Grades. Please review the requirements at www.ieee.org for eligibility.

Eligible candidates are requested to send in their resumes to Dr. Vasudeva P. Atluri, Membership Development Coordinator, at vpatluri@ieee.org and Dr. Charles E. Weitzel, Section Chair, at c.weitzel@ieee.org for consideration.

Phoenix Section LinkedIn Group

If you are interested in professional networking and shared Section related updates & discussions join the IEEE Phoenix Section Group on LinkedIn. Signing up only takes minutes and is free. A job board is available as well.

You can also go to IEEE Phoenix Section LinkdIn page by clicking in button on the IEEE Phoenix Section home page

IEEE Phoenix Section Ventures into Social Media

You can access the web page three ways:
Use the URL: https://www.facebook.com/IEEEPhoenixSection
Click on the Facebook logo f link from IEEE Phoenix section home page.
Search for IEEE Phoenix Section from your Facebook page.

We need following help.

1. Each of you access the IEEE Phoenix Section Web page and click on "Like" hyperlink.
2. Go on the Friends section of the page and "Invite Your Friends." Once your click on Invite button, it will get your email contact list. Your facebook contact list will already be populated with your Facebook friends and you can simply click the Invite button next to their name. Please invite as many friends as you can.
3. Provide me the contents for posting on a regular basis - meeting/ event announcements, Event pictures, Videos.
4. Start some discussion topics under - Status section.

IEEE Membership Grade Advancement

IEEE Phoenix Section Executive Committee encourages all to apply for advancement in membership grade to Senior Member and Fellow Grade. Please review the requirements at www.ieee.org. Please contact IEEE Phoenix Section Membership Development Chair, Dr. Vasudeva P. Atluri, at vpatluri@ieee.org for additional information.

Enhanced Senior Member Application Launched

Effective 29 July 2011, IEEE Admission and Advancement launched a new Senior Member Application. The new application includes numerous enhancements, based on feedback from volunteers and members, including:

- New user friendly format / design
- Secure environment (need IEEE Web account)
- Ability to save application in “draft” form
- Ability to upload resume or Curriculum Vitae (up to 3 MB)
- Applicant can view application online
- Applicant can view status of requested reference forms
- References will be notified by email to provide applicant reference
- References will have the ability to view their completed reference form(s)
- Real time application status

The goal is to provide prospective Senior Members with an easy to use and intuitive interface, while streamlining internal operations at the same time. View the new Senior Member application.

IEEE Member’s Benefits

IEEE-USA’s Free E-Books to Members Give Perspectives on Leading & Managing & Guidance on Survivor Planning

July Free E-Book

IEEE-USA will offer “Leading and Managing Engineering and Technology – Book 1: Perspectives on Leading and Managing” free to IEEE members in July.

Author and IEEE Life Fellow Gerard H. “Gus” Gaynor writes that the competencies needed to lead and manage continue to be misunderstood. As a society, he says, we focus on leadership demonstrated by politicians, industry executives and individual effort related to some major accomplishment.

“Perspectives on Leading and Managing” takes a step beyond the usual focus on leadership to explore the following questions:

* Are leading and managing different, the same or complementary?
* Is it possible to lead without managing?
* Is it possible to manage without leading?
* Does the technical professional have a greater role in leading and managing?

“Leading and Managing Engineering and Technology, Book 1: Perspectives on Leading and Managing” can be downloaded at http://www.ieeeusa.org/communications/ebooks/files/jul14/28vniz3/Leading-and-Managing-Engineering-and-Technology-Book-1.pdf for free to IEEE members. The nonmember cost is $9.99.

To purchase IEEE member-only products, and to receive the member discount on eligible products, you must log in with your IEEE Web account.

August Free E-Book

In August, IEEE-USA will offer “Survivor Planning: What Every Spouse Should Know,” by the late George F. McClure.

In this practical reference, McClure urges readers “not to leave your family in the dark, digging to find important documents and information. Life has to go on after a spouse, partner, or parent passes away. Dealing with the myriad of decision processes immediately following a death in the family is a confusing ordeal.”

“Survivor Planning” gives guidance in advance planning, retirement benefits, wills, living trusts and finances. It also has a checklist that will help you organize all the important information you will need and Websites where you can find additional assistance.

This e-book will be available free to members in August.

Call for Authors

IEEE-USA E-books seek authors to write an e-book, or an e-book series, on career guidance and development topics. If you have an e-book idea that will benefit members on a particular topic of expertise, email your proposal to IEEE-USA Publishing Manager Georgia C. Stelluto at g.stelluto@ieee.org, and IEEE-USA Communications Committee Chair Gus Gaynor at g.gaynor@ieee.org.

IEEE-USA serves the public good and promotes the careers and public policy interests of more than 200,000 engineering, computing and technology professionals who are U.S. members of IEEE.

Web: www.ieeeusa.org
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Contact: Sharon C. Richardson, Coordinator
IEEE-USA Communications & Publishing
Phone: 1 202 530 8363
E-mail: s.richardson@ieee.org

GoogleApps@IEEE Now Available to IEEE Members

GoogleApps@IEEE is a suite of products offered to IEEE members to enhance peer-to-peer communications and collaboration. The suite of applications includes e-mail, calendaring, contacts, and document sharing along with other collaborative tools. 30G of available cloud storage memory is available for these applications. Learn more about http://www.ieee.org/googleapps

GoogleApps@IEEE is available to members at no additional cost, bringing access to:

- A unique IEEE e-mail address (e.g., John.A.Doe@ieee.org);
- Mail forwarding or e-mail inbox (Gmail);
- 30-gigabytes of shared storage (Gmail and Google Drive);
- 99.9 percent up time guaranteed by Google;
- Advertisement-free Gmail;
- Files stored in the cloud for easy sharing and access from anywhere via Google Drive.